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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, SD, SPI, UART/USART, USB, USB OTG
Peripherals	DMA, I ² S, LVD, POR, PWM, WDT
Number of I/O	100
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 58x16b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LBGA
Supplier Device Package	144-MAPBGA (13x13)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mk60fn1m0vmd12r

- Communication interfaces
 - Ethernet controller with MII and RMII interface to external PHY and hardware IEEE 1588 capability
 - USB high-/full-/low-speed On-the-Go controller with ULPI interface
 - USB full-/low-speed On-the-Go controller with on-chip transceiver
 - USB Device Charger detect (USBDCD)
 - Two Controller Area Network (CAN) modules
 - Three SPI modules
 - Two I2C modules
 - Six UART modules
 - Secure Digital Host Controller (SDHC)
 - Two I2S modules



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Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Output high voltage — low drive strength • $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OH} = -2\text{ mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OH} = -0.6\text{ mA}$	$V_{DD} - 0.5$ $V_{DD} - 0.5$	— —	— —	V V	
I_{OHT}	Output high current total for all ports	—	—	100	mA	
I_{OHT_io60}	Output high current total for fast digital ports	—	—	100	mA	
V_{OL}	Output low voltage — high drive strength • $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 10\text{ mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 5\text{ mA}$	— —	— —	0.5 0.5	V V	
	Output low voltage — low drive strength • $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 2\text{ mA}$ • $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 1\text{ mA}$	— —	— —	0.5 0.5	V V	
I_{OLT}	Output low current total for all ports	—	—	100	mA	
I_{OLT_io60}	Output low current total for fast digital ports	—	—	100	mA	
I_{INA}	Input leakage current, analog pins and digital pins configured as analog inputs • $V_{SS} \leq V_{IN} \leq V_{DD}$ • All pins except EXTAL32, XTAL32, EXTAL, XTAL • EXTAL (PTA18) and XTAL (PTA19) • EXTAL32, XTAL32	—	0.002	0.5	μA	1, 2
		—	0.004	1.5	μA	
		—	0.075	10	μA	
I_{IND}	Input leakage current, digital pins • $V_{SS} \leq V_{IN} \leq V_{IL}$ • All digital pins • $V_{IN} = V_{DD}$ • All digital pins except PTD7 • PTD7	—	0.002	0.5	μA	2, 3
		—	0.002	0.5	μA	
		—	0.004	1	μA	
I_{IND}	Input leakage current, digital pins • $V_{IL} < V_{IN} < V_{DD}$ • $V_{DD} = 3.6\text{ V}$ • $V_{DD} = 3.0\text{ V}$ • $V_{DD} = 2.5\text{ V}$ • $V_{DD} = 1.7\text{ V}$	—	18	26	μA	2, 3, 4
		—	12	19	μA	
		—	8	13	μA	
		—	3	6	μA	
I_{IND}	Input leakage current, digital pins • $V_{DD} < V_{IN} < 5.5\text{ V}$	—	1	50	μA	2, 3
Z_{IND}	Input impedance examples, digital pins	—	—	48	k Ω	2, 5

Table continues on the next page...

Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	$V_{DD} = 3.6\text{ V}$ $V_{DD} = 3.0\text{ V}$ $V_{DD} = 2.5\text{ V}$ $V_{DD} = 1.7\text{ V}$	—	—	55	k Ω	
R_{PU}	Internal pullup resistors	20	—	50	k Ω	6
R_{PD}	Internal pulldown resistors	20	—	50	k Ω	7

1. Analog pins are defined as pins that do not have an associated general purpose I/O port function.
2. Digital pins have an associated GPIO port function and have 5V tolerant inputs, except EXTAL and XTAL.
3. Internal pull-up/pull-down resistors disabled.
4. Characterized, not tested in production.
5. Examples calculated using V_{IL} relation, V_{DD} , and max I_{IND} : $Z_{IND} = V_{IL} / I_{IND}$. This is the impedance needed to pull a high signal to a level below V_{IL} due to leakage when $V_{IL} < V_{IN} < V_{DD}$. These examples assume signal source low = 0 V. See [Figure 2](#).
6. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{SS}$
7. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{DD}$

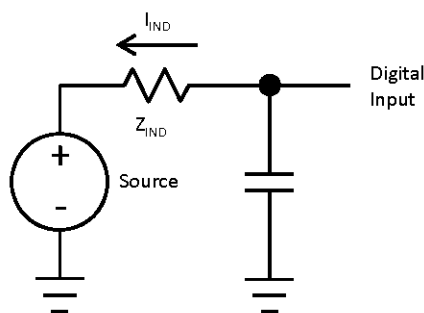


Figure 2. 5 V Tolerant Input I_{IND} Parameter

5.2.4 Power mode transition operating behaviors

All specifications except t_{POR} , and $V_{LLSx} \rightarrow \text{RUN}$ recovery times in the following table assume this clock configuration:

- CPU and system clocks = 100 MHz
- Bus clock = 50 MHz
- FlexBus clock = 50 MHz
- Flash clock = 25 MHz
- MCG mode: FEI

5. 4 MHz core, system, 2 MHz FlexBus, and 2 MHz bus clock and 0.5 MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled.
6. Includes 32kHz oscillator current and RTC operation.

5.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

- MCG in FBE mode for 50 MHz and lower frequencies. MCG in FEE mode at greater than 50 MHz frequencies. MCG in PEE mode at greater than 100 MHz frequencies.
- USB regulator disabled
- No GPIOs toggled
- Code execution from flash with cache enabled
- For the ALLOFF curve, all peripheral clocks are disabled except FTFE

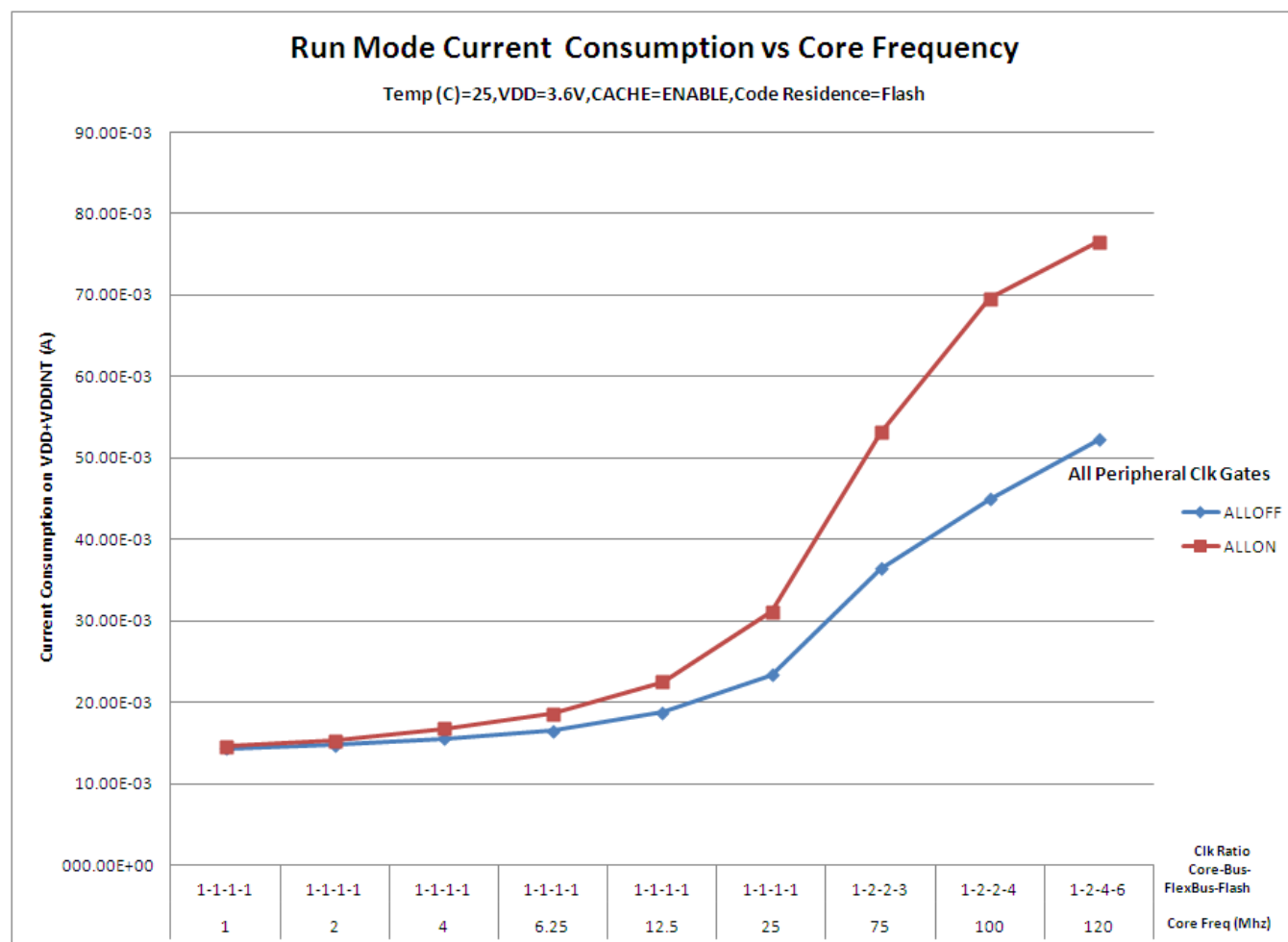


Figure 3. Run mode supply current vs. core frequency

Table 9. Device clock specifications (continued)

Symbol	Description	Min.	Max.	Unit	Notes
f _{BUS}	Bus clock	—	4	MHz	
FB_CLK	FlexBus clock	—	4	MHz	
f _{FLASH}	Flash clock	—	0.5	MHz	
f _{LPTMR}	LPTMR clock	—	4	MHz	

1. The frequency limitations in VLPR mode here override any frequency specification listed in the timing specification for any other module.

5.3.2 General switching specifications

These general purpose specifications apply to all pins configured for:

- GPIO signaling
- Other peripheral module signaling not explicitly stated elsewhere

Table 10. General switching specifications

Symbol	Description	Min.	Max.	Unit	Notes
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1, 2
	GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter enabled) — Asynchronous path	100	—	ns	3
	GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter disabled) — Asynchronous path	16	—	ns	3
	External reset pulse width (digital glitch filter disabled)	100	—	ns	3
	Mode select (EZP_CS) hold time after reset deassertion	2	—	Bus clock cycles	
	Port rise and fall time (high drive strength) • Slew disabled • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ • Slew enabled • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$	— — — —	14 8 36 24	ns ns ns ns	4
	Port rise and fall time (low drive strength) • Slew disabled • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ • Slew enabled • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$	— — — —	14 8 36 24	ns ns ns ns	5

Table continues on the next page...

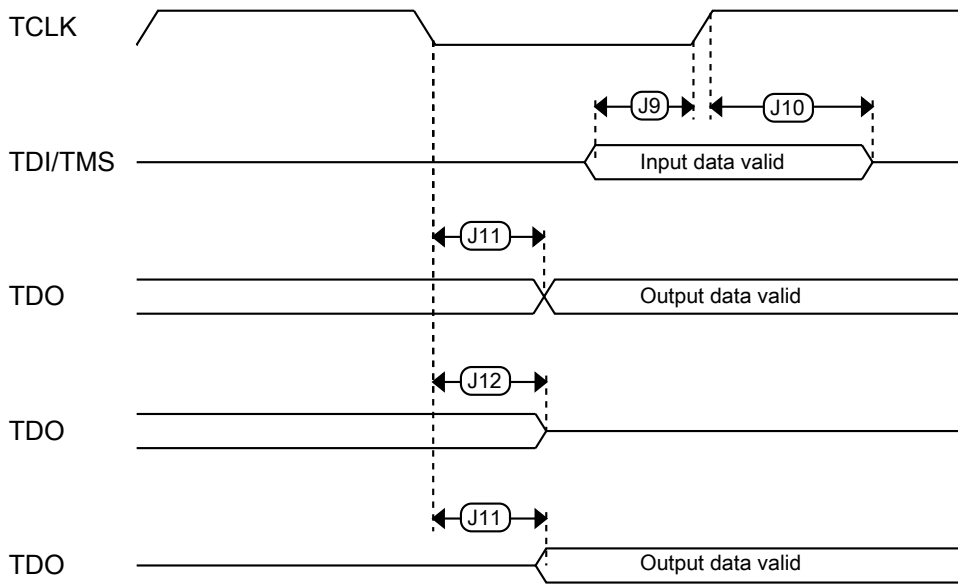


Figure 9. Test Access Port timing

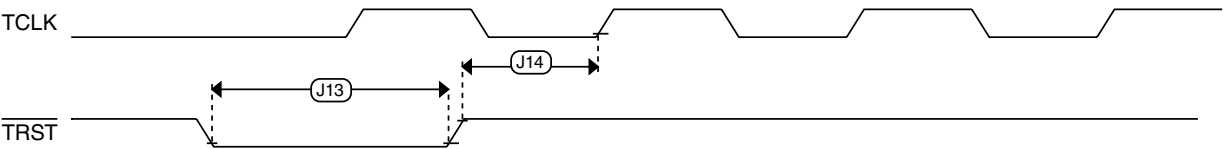


Figure 10. $\overline{\text{TRST}}$ timing

6.2 System modules

There are no specifications necessary for the device's system modules.

6.3 Clock modules

6.3.1 MCG specifications

Table 15. MCG specifications

Symbol	Description		Min.	Typ.	Max.	Unit	Notes
f _{ints_ft}	Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C		—	32.768	—	kHz	
f _{ints_t}	Internal reference frequency (slow clock) — user trimmed		31.25	—	39.0625	kHz	
Δf _{dco_res_t}	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM		—	± 0.3	± 0.6	%f _{dco}	1
Δf _{dco_res_t}	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM only		—	± 0.2	± 0.5	%f _{dco}	1
Δf _{dco_t}	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C		—	± 4.5	—	%f _{dco}	1
f _{intf_ft}	Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C		—	4	—	MHz	
f _{intf_t}	Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C		3	—	5	MHz	
f _{loc_low}	Loss of external clock minimum frequency — RANGE = 00		(3/5) x f _{ints_t}	—	—	kHz	
f _{loc_high}	Loss of external clock minimum frequency — RANGE = 01, 10, or 11		(16/5) x f _{ints_t}	—	—	kHz	
FLL							
f _{fll_ref}	FLL reference frequency range		31.25	—	39.0625	kHz	
f _{dco}	DCO output frequency range	Low range (DRS=00) 640 × f _{fll_ref}	20	20.97	25	MHz	2, 3
		Mid range (DRS=01) 1280 × f _{fll_ref}	40	41.94	50	MHz	
		Mid-high range (DRS=10) 1920 × f _{fll_ref}	60	62.91	75	MHz	
		High range (DRS=11) 2560 × f _{fll_ref}	80	83.89	100	MHz	
f _{dco_t_DMx32}	DCO output frequency	Low range (DRS=00) 732 × f _{fll_ref}	—	23.99	—	MHz	4, 5
		Mid range (DRS=01) 1464 × f _{fll_ref}	—	47.97	—	MHz	
		Mid-high range (DRS=10) 2197 × f _{fll_ref}	—	71.99	—	MHz	
		High range (DRS=11) 2929 × f _{fll_ref}	—	95.98	—	MHz	
J _{cyc_fll}	FLL period jitter		—	180	—	ps	

Table continues on the next page...

6.4.1.3 Flash high voltage current behaviors

Table 22. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I _{DD_PGM}	Average current adder during high voltage flash programming operation	—	3.5	7.5	mA
I _{DD_ERS}	Average current adder during high voltage flash erase operation	—	1.5	4.0	mA

6.4.1.4 Reliability specifications

Table 23. NVM reliability specifications

Symbol	Description	Min.	Typ. ¹	Max.	Unit	Notes
Program Flash						
t _{nvmretp10k}	Data retention after up to 10 K cycles	5	50	—	years	
t _{nvmretp1k}	Data retention after up to 1 K cycles	20	100	—	years	
n _{nvmcycp}	Cycling endurance	10 K	50 K	—	cycles	2
Data Flash						
t _{nvmretd10k}	Data retention after up to 10 K cycles	5	50	—	years	
t _{nvmretd1k}	Data retention after up to 1 K cycles	20	100	—	years	
n _{nvmcycd}	Cycling endurance	10 K	50 K	—	cycles	2
FlexRAM as EEPROM						
t _{nvmretee100}	Data retention up to 100% of write endurance	5	50	—	years	
t _{nvmretee10}	Data retention up to 10% of write endurance	20	100	—	years	
n _{nvmcycee}	Cycling endurance for EEPROM backup	20 K	50 K	—	cycles	2
n _{nvmwree16}	Write endurance	70 K	175 K	—	writes	3
n _{nvmwree128}	• EEPROM backup to FlexRAM ratio = 16	630 K	1.6 M	—	writes	
n _{nvmwree512}	• EEPROM backup to FlexRAM ratio = 128	2.5 M	6.4 M	—	writes	
n _{nvmwree2k}	• EEPROM backup to FlexRAM ratio = 512	10 M	25 M	—	writes	
	• EEPROM backup to FlexRAM ratio = 2,048					

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25°C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at -40°C ≤ T_j ≤ 125°C.
3. Write endurance represents the number of writes to each FlexRAM location at -40°C ≤ T_j ≤ 125°C influenced by the cycling endurance of the FlexNVM and the allocated EEPROM backup per subsystem. Minimum and typical values assume all 16-bit or 32-bit writes to FlexRAM; all 8-bit writes result in 50% less endurance.

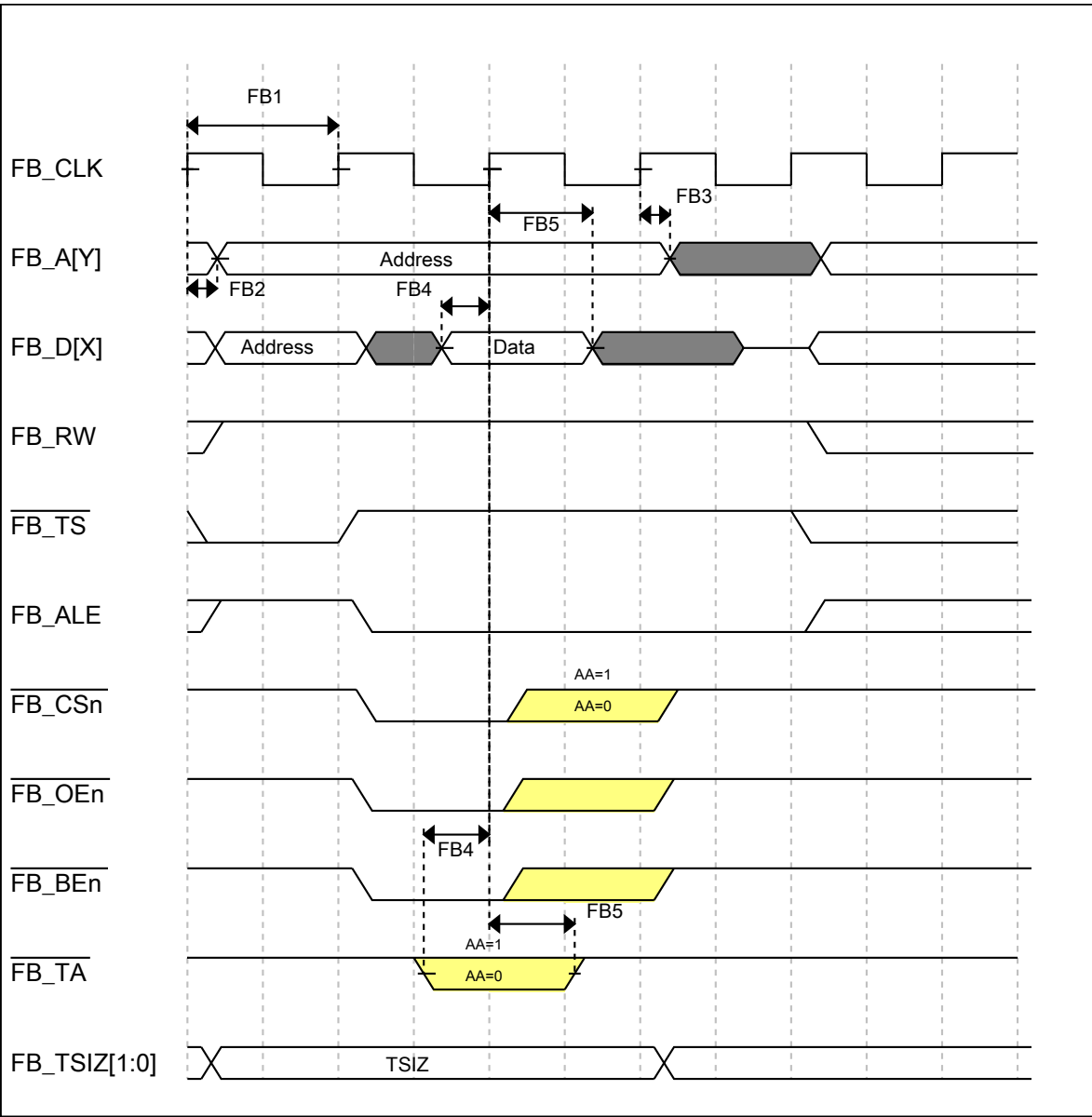


Figure 18. FlexBus read timing diagram

6.6.1 ADC electrical specifications

The 16-bit accuracy specifications listed in [Table 28](#) and [Table 29](#) are achievable on the differential pins ADCx_DP0, ADCx_DM0.

The ADCx_DP2 and ADCx_DM2 ADC inputs are connected to the PGA outputs and are not direct device pins. Accuracy specifications for these pins are defined in [Table 30](#) and [Table 31](#).

All other ADC channels meet the 13-bit differential/12-bit single-ended accuracy specifications.

6.6.1.1 16-bit ADC operating conditions

Table 28. 16-bit ADC operating conditions

Symbol	Description	Conditions	Min.	Typ. ¹	Max.	Unit	Notes
V _{DDA}	Supply voltage	Absolute	1.71	—	3.6	V	
ΔV _{DDA}	Supply voltage	Delta to V _{DD} (V _{DD} – V _{DDA})	-100	0	+100	mV	2
ΔV _{SSA}	Ground voltage	Delta to V _{SS} (V _{SS} – V _{SSA})	-100	0	+100	mV	2
V _{REFH}	ADC reference voltage high		1.13	V _{DDA}	V _{DDA}	V	
V _{REFL}	ADC reference voltage low		V _{SSA}	V _{SSA}	V _{SSA}	V	
V _{ADIN}	Input voltage	16-bit differential mode - All other modes	V _{REFL} V _{REFL}	— —	31/32 × V _{REFH} V _{REFH}	V	
C _{ADIN}	Input capacitance	16-bit mode 8-bit / 10-bit / 12-bit modes	— —	8 4	10 5	pF	
R _{ADIN}	Input series resistance		—	2	5	kΩ	
R _{AS}	Analog source resistance (external)	13-bit / 12-bit modes f _{ADCK} < 4 MHz	—	—	5	kΩ	3
f _{ADCK}	ADC conversion clock frequency	≤ 13-bit mode	1.0	—	18.0	MHz	4
f _{ADCK}	ADC conversion clock frequency	16-bit mode	2.0	—	12.0	MHz	4
C _{rate}	ADC conversion rate	≤ 13-bit modes No ADC hardware averaging Continuous conversions enabled, subsequent conversion time	20.000	—	818.330	ksps	5
C _{rate}	ADC conversion rate	16-bit mode No ADC hardware averaging	37.037	—	461.467	ksps	5

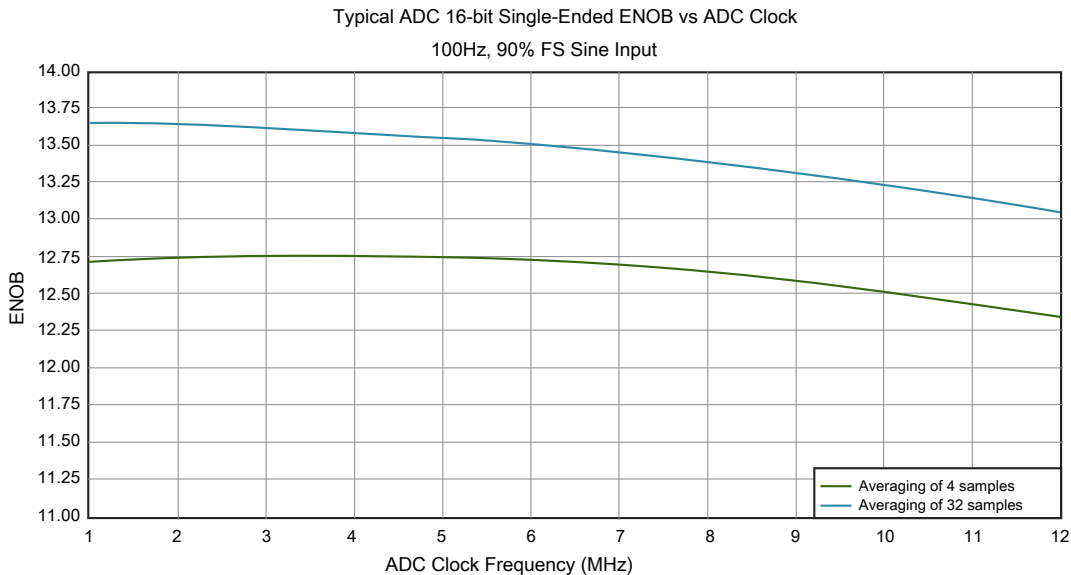


Figure 22. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

6.6.1.3 16-bit ADC with PGA operating conditions

Table 30. 16-bit ADC with PGA operating conditions

Symbol	Description	Conditions	Min.	Typ. ¹	Max.	Unit	Notes
V _{DDA}	Supply voltage	Absolute	1.71	—	3.6	V	
V _{REFPGA}	PGA ref voltage		V _{REF_OU_T}	V _{REF_OU_T}	V _{REF_OU_T}	V	2, 3
V _{ADIN}	Input voltage		V _{SSA}	—	V _{DDA}	V	
V _{CM}	Input Common Mode range		V _{SSA}	—	V _{DDA}	V	
R _{PGAD}	Differential input impedance	Gain = 1, 2, 4, 8 Gain = 16, 32 Gain = 64	— — —	128 64 32	— — —	kΩ	IN+ to IN- ⁴
R _{AS}	Analog source resistance		—	100	—	Ω	5
T _S	ADC sampling time		1.25	—	—	μs	6
C _{rate}	ADC conversion rate	≤ 13 bit modes No ADC hardware averaging Continuous conversions enabled Peripheral clock = 50 MHz	18.484	—	450	Ksps	7
		16 bit modes	37.037	—	250	Ksps	8

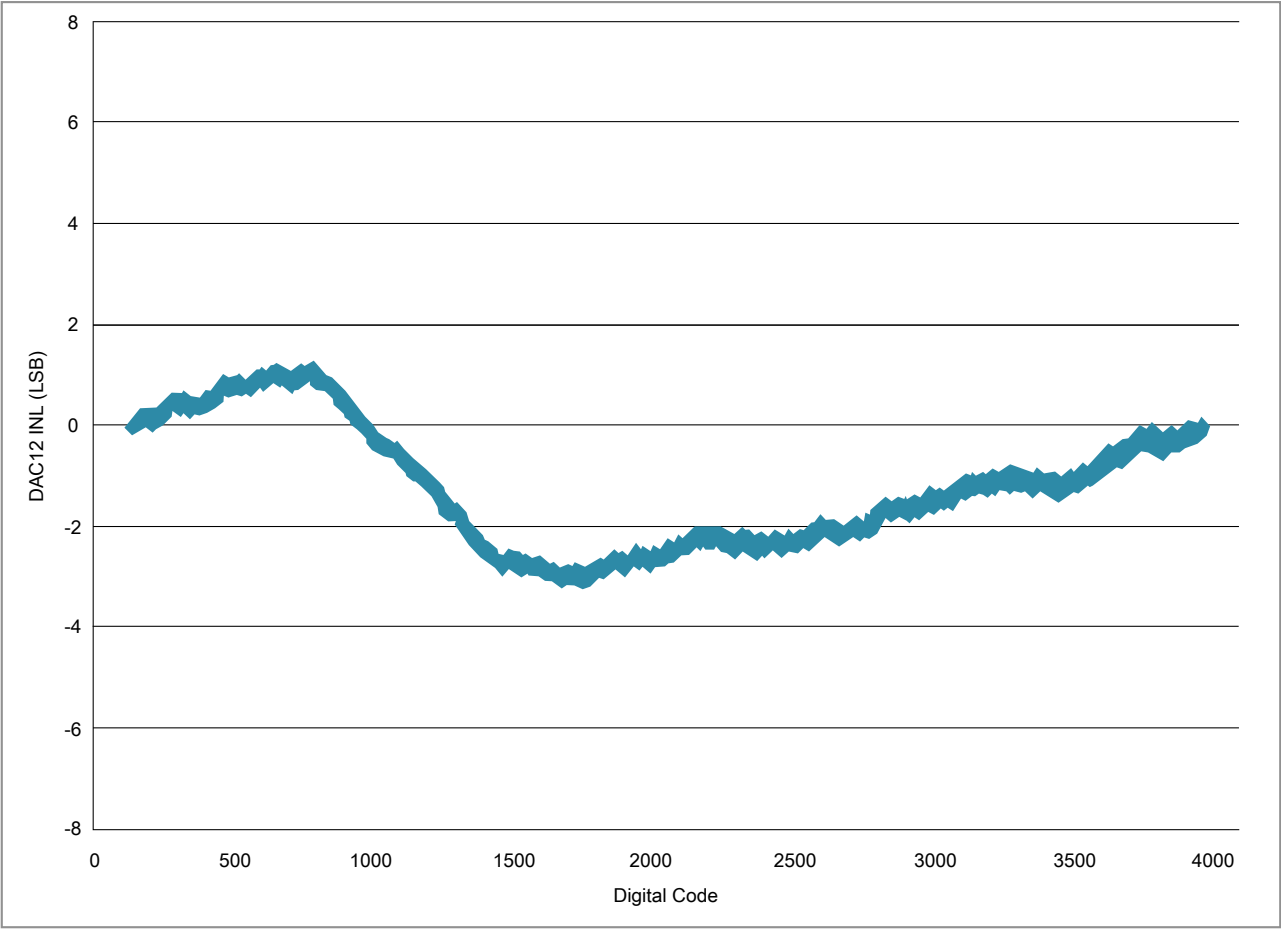


Figure 25. Typical INL error vs. digital code

6.8.5 ULPI timing specifications

The ULPI interface is fully compliant with the industry standard UTMI+ Low Pin Interface. Control and data timing requirements for the ULPI pins are given in the following table. These timings apply to synchronous mode only. All timings are measured with respect to the clock as seen at the USB_CLKIN pin.

Table 43. ULPI timing specifications

Num	Description	Min.	Typ.	Max.	Unit
	USB_CLKIN operating frequency	—	60	—	MHz
	USB_CLKIN duty cycle	—	50	—	%
U1	USB_CLKIN clock period	—	16.67	—	ns
U2	Input setup (control and data)	5	—	—	ns
U3	Input hold (control and data)	1	—	—	ns
U4	Output valid (control and data)	—	—	9.5	ns
U5	Output hold (control and data)	1	—	—	ns

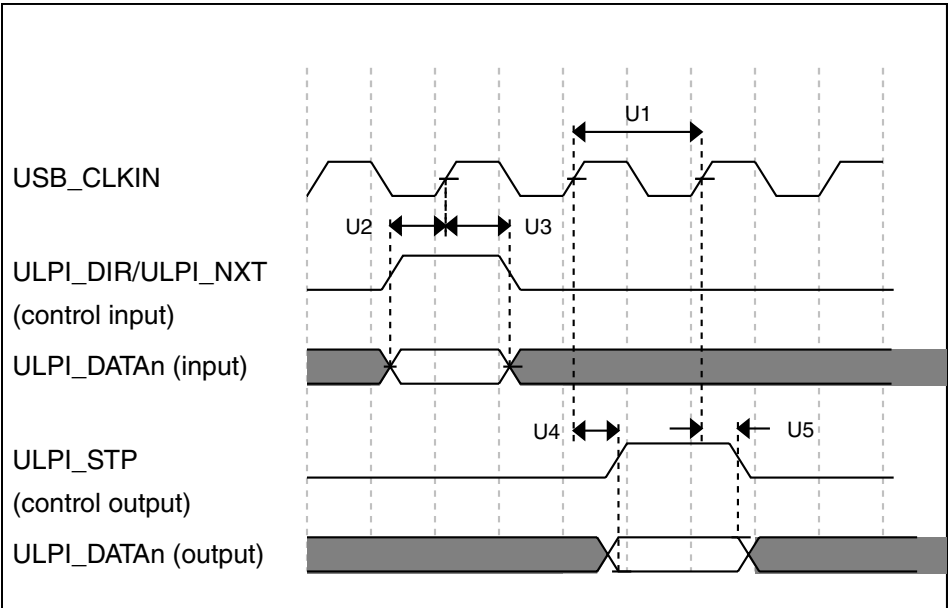


Figure 29. ULPI timing diagram

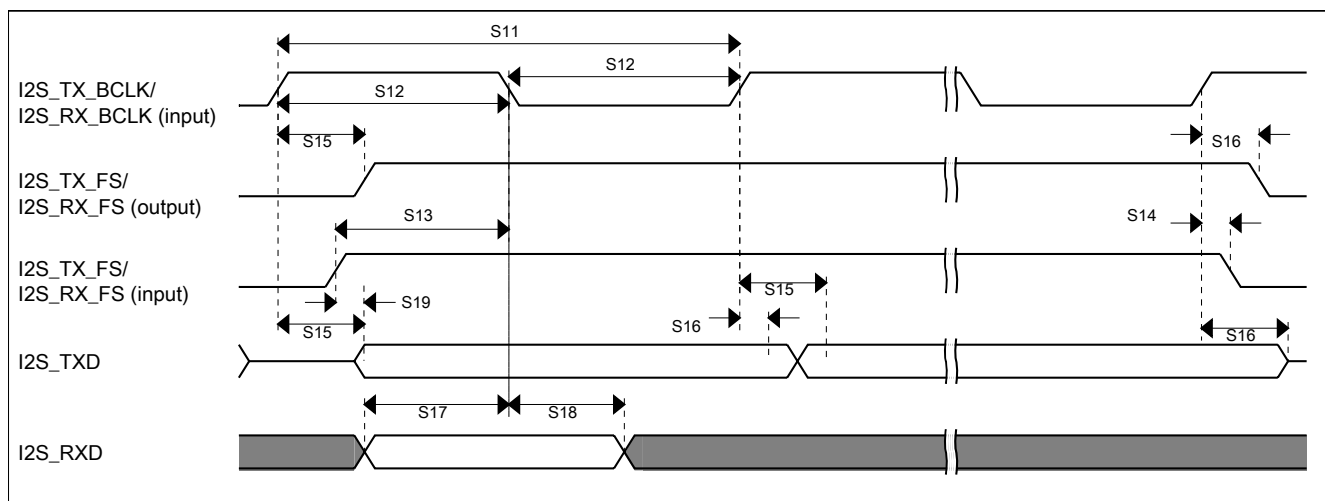


Figure 39. I2S/SAI timing — slave modes

6.8.12.3 VLPR, VLPW, and VLPS mode performance over the full operating voltage range

This section provides the operating performance over the full operating voltage for the device in VLPR, VLPW, and VLPS modes.

Table 55. I2S/SAI master mode timing in VLPR, VLPW, and VLPS modes (full voltage range)

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S1	I2S_MCLK cycle time	62.5	—	ns
S2	I2S_MCLK pulse width high/low	45%	55%	MCLK period
S3	I2S_TX_BCLK/I2S_RX_BCLK cycle time (output)	250	—	ns
S4	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low	45%	55%	BCLK period
S5	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid	—	45	ns
S6	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid	0	—	ns
S7	I2S_TX_BCLK to I2S_TXD valid	—	45	ns
S8	I2S_TX_BCLK to I2S_TXD invalid	-1.6	—	ns
S9	I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK	45	—	ns
S10	I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK	0	—	ns

Table 58. Pins with active pull control after reset

Pin	Active pull direction after reset
PTA0	pulldown
PTA1	pullup
PTA3	pullup
PTA4	pullup
RESET_b	pullup

8.2 K60 Signal Multiplexing and Pin Assignments

The following table shows the signals available on each pin and the locations of these pins on the devices supported by this document. The Port Control Module is responsible for selecting which ALT functionality is available on each pin.

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
—	L5	RTC_WAKEUP_B	RTC_WAKEUP_B	RTC_WAKEUP_B								
—	M5	NC	NC	NC								
—	A10	NC	NC	NC								
—	B10	NC	NC	NC								
—	C10	NC	NC	NC								
1	D3	PTE0	ADC1_SE4a	ADC1_SE4a	PTE0	SPI1_PCS1	UART1_TX	SDHC0_D1		I2C1_SDA	RTC_CLKOUT	
2	D2	PTE1/LLWU_P0	ADC1_SE5a	ADC1_SE5a	PTE1/LLWU_P0	SPI1_SOUT	UART1_RX	SDHC0_D0		I2C1_SCL	SPI1_SIN	
3	D1	PTE2/LLWU_P1	ADC1_SE6a	ADC1_SE6a	PTE2/LLWU_P1	SPI1_SCK	UART1_CTS_b	SDHC0_DCLK				
4	E4	PTE3	ADC1_SE7a	ADC1_SE7a	PTE3	SPI1_SIN	UART1_RTS_b	SDHC0_CMD			SPI1_SOUT	
5	E5	VDD	VDD	VDD								
6	F6	VSS	VSS	VSS								
7	E3	PTE4/LLWU_P2	DISABLED		PTE4/LLWU_P2	SPI1_PCS0	UART3_TX	SDHC0_D3				
8	E2	PTE5	DISABLED		PTE5	SPI1_PCS2	UART3_RX	SDHC0_D2		FTM3_CH0		
9	E1	PTE6	DISABLED		PTE6	SPI1_PCS3	UART3_CTS_b	I2S0_MCLK		FTM3_CH1	USB_SOF_OUT	
10	F4	PTE7	DISABLED		PTE7		UART3_RTS_b	I2S0_RXD0		FTM3_CH2		
11	F3	PTE8	ADC2_SE16	ADC2_SE16	PTE8	I2S0_RXD1	UART5_TX	I2S0_RX_FS		FTM3_CH3		
12	F2	PTE9	ADC2_SE17	ADC2_SE17	PTE9	I2S0_TXD1	UART5_RX	I2S0_RX_BCLK		FTM3_CH4		

Pinout

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
13	F1	PTE10	DISABLED		PTE10		UART5_CTS_b	I2S0_TXD0		FTM3_CH5		
14	G4	PTE11	ADC3_SE16	ADC3_SE16	PTE11		UART5_RTS_b	I2S0_TX_FS		FTM3_CH6		
15	G3	PTE12	ADC3_SE17	ADC3_SE17	PTE12			I2S0_TX_BCLK		FTM3_CH7		
16	E6	VDD	VDD	VDD								
17	F7	VSS	VSS	VSS								
18	H3	VSS	VSS	VSS								
19	H1	USB0_DP	USB0_DP	USB0_DP								
20	H2	USB0_DM	USB0_DM	USB0_DM								
21	G1	VOUT33	VOUT33	VOUT33								
22	G2	VREGIN	VREGIN	VREGIN								
23	J1	PGA2_DP/ ADC2_DP0/ ADC3_DP3/ ADC0_DP1	PGA2_DP/ ADC2_DP0/ ADC3_DP3/ ADC0_DP1	PGA2_DP/ ADC2_DP0/ ADC3_DP3/ ADC0_DP1								
24	J2	PGA2_DM/ ADC2_DM0/ ADC3_DM3/ ADC0_DM1	PGA2_DM/ ADC2_DM0/ ADC3_DM3/ ADC0_DM1	PGA2_DM/ ADC2_DM0/ ADC3_DM3/ ADC0_DM1								
25	K1	PGA3_DP/ ADC3_DP0/ ADC2_DP3/ ADC1_DP1	PGA3_DP/ ADC3_DP0/ ADC2_DP3/ ADC1_DP1	PGA3_DP/ ADC3_DP0/ ADC2_DP3/ ADC1_DP1								
26	K2	PGA3_DM/ ADC3_DM0/ ADC2_DM3/ ADC1_DM1	PGA3_DM/ ADC3_DM0/ ADC2_DM3/ ADC1_DM1	PGA3_DM/ ADC3_DM0/ ADC2_DM3/ ADC1_DM1								
27	L1	PGA0_DP/ ADC0_DP0/ ADC1_DP3	PGA0_DP/ ADC0_DP0/ ADC1_DP3	PGA0_DP/ ADC0_DP0/ ADC1_DP3								
28	L2	PGA0_DM/ ADC0_DM0/ ADC1_DM3	PGA0_DM/ ADC0_DM0/ ADC1_DM3	PGA0_DM/ ADC0_DM0/ ADC1_DM3								
29	M1	PGA1_DP/ ADC1_DP0/ ADC0_DP3	PGA1_DP/ ADC1_DP0/ ADC0_DP3	PGA1_DP/ ADC1_DP0/ ADC0_DP3								
30	M2	PGA1_DM/ ADC1_DM0/ ADC0_DM3	PGA1_DM/ ADC1_DM0/ ADC0_DM3	PGA1_DM/ ADC1_DM0/ ADC0_DM3								
31	H5	VDDA	VDDA	VDDA								
32	G5	VREFH	VREFH	VREFH								
33	G6	VREFL	VREFL	VREFL								
34	H6	VSSA	VSSA	VSSA								
35	K3	ADC1_SE16/ CMP2_IN2/ ADC0_SE22	ADC1_SE16/ CMP2_IN2/ ADC0_SE22	ADC1_SE16/ CMP2_IN2/ ADC0_SE22								

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
83	G12	PTB2	ADC0_SE12/ TSIO_CH7	ADC0_SE12/ TSIO_CH7	PTB2	I2C0_SCL	UART0_ RTS_b	ENET0_ 1588_TMR0		FTM0_FLT3		
84	G11	PTB3	ADC0_SE13/ TSIO_CH8	ADC0_SE13/ TSIO_CH8	PTB3	I2C0_SDA	UART0_ CTS_b/ UART0_ COL_b	ENET0_ 1588_TMR1		FTM0_FLT0		
85	G10	PTB4	ADC1_SE10	ADC1_SE10	PTB4			ENET0_ 1588_TMR2		FTM1_FLT0		
86	G9	PTB5	ADC1_SE11	ADC1_SE11	PTB5			ENET0_ 1588_TMR3		FTM2_FLT0		
87	F12	PTB6	ADC1_SE12	ADC1_SE12	PTB6				FB_AD23			
88	F11	PTB7	ADC1_SE13	ADC1_SE13	PTB7				FB_AD22			
89	F10	PTB8	DISABLED		PTB8		UART3_ RTS_b		FB_AD21			
90	F9	PTB9	DISABLED		PTB9	SPI1_PCS1	UART3_ CTS_b		FB_AD20			
91	E12	PTB10	ADC1_SE14	ADC1_SE14	PTB10	SPI1_PCS0	UART3_RX	I2S1_TX_ BCLK	FB_AD19	FTM0_FLT1		
92	E11	PTB11	ADC1_SE15	ADC1_SE15	PTB11	SPI1_SCK	UART3_TX	I2S1_TX_FS	FB_AD18	FTM0_FLT2		
93	H7	VSS	VSS	VSS								
94	F5	VDD	VDD	VDD								
95	E10	PTB16	TSIO_CH9	TSIO_CH9	PTB16	SPI1_SOUT	UART0_RX	I2S1_TXD0	FB_AD17	EWM_IN		
96	E9	PTB17	TSIO_CH10	TSIO_CH10	PTB17	SPI1_SIN	UART0_TX	I2S1_TXD1	FB_AD16	EWM_OUT_b		
97	D12	PTB18	TSIO_CH11	TSIO_CH11	PTB18	CAN0_TX	FTM2_CH0	I2S0_TX_ BCLK	FB_AD15	FTM2_QD_ PHA		
98	D11	PTB19	TSIO_CH12	TSIO_CH12	PTB19	CAN0_RX	FTM2_CH1	I2S0_TX_FS	FB_OE_b	FTM2_QD_ PHB		
99	D10	PTB20	ADC2_SE4a	ADC2_SE4a	PTB20	SPI2_PCS0			FB_AD31/ NFC_ DATA15	CMP0_OUT		
100	D9	PTB21	ADC2_SE5a	ADC2_SE5a	PTB21	SPI2_SCK			FB_AD30/ NFC_ DATA14	CMP1_OUT		
101	C12	PTB22	DISABLED		PTB22	SPI2_SOUT			FB_AD29/ NFC_ DATA13	CMP2_OUT		
102	C11	PTB23	DISABLED		PTB23	SPI2_SIN	SPI0_PCS5		FB_AD28/ NFC_ DATA12	CMP3_OUT		
103	B12	PTC0	ADC0_SE14/ TSIO_CH13	ADC0_SE14/ TSIO_CH13	PTC0	SPI0_PCS4	PDB0_ EXTRG		FB_AD14/ NFC_ DATA11	I2S0_TXD1		
104	B11	PTC1/ LLWU_P6	ADC0_SE15/ TSIO_CH14	ADC0_SE15/ TSIO_CH14	PTC1/ LLWU_P6	SPI0_PCS3	UART1_ RTS_b	FTM0_CH0	FB_AD13/ NFC_ DATA10	I2S0_TXD0		
105	A12	PTC2	ADC0_SE4b/ CMP1_IN0/ TSIO_CH15	ADC0_SE4b/ CMP1_IN0/ TSIO_CH15	PTC2	SPI0_PCS2	UART1_ CTS_b	FTM0_CH1	FB_AD12/ NFC_DATA9	I2S0_TX_FS		

144 LQFP	144 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	EzPort
106	A11	PTC3/ LLWU_P7	CMP1_IN1	CMP1_IN1	PTC3/ LLWU_P7	SPI0_PCS1	UART1_RX	FTM0_CH2	CLKOUT	I2S0_TX_ BCLK		
107	H8	VSS	VSS	VSS								
108	—	VDD	VDD	VDD								
109	A9	PTC4/ LLWU_P8	DISABLED		PTC4/ LLWU_P8	SPI0_PCS0	UART1_TX	FTM0_CH3	FB_AD11/ NFC_DATA8	CMP1_OUT	I2S1_TX_ BCLK	
110	D8	PTC5/ LLWU_P9	DISABLED		PTC5/ LLWU_P9	SPI0_SCK	LPTMR0_ ALT2	I2S0_RXD0	FB_AD10/ NFC_DATA7	CMP0_OUT	I2S1_TX_FS	
111	C8	PTC6/ LLWU_P10	CMP0_IN0	CMP0_IN0	PTC6/ LLWU_P10	SPI0_SOUT	PDB0_ EXTRG	I2S0_RX_ BCLK	FB_AD9/ NFC_DATA6	I2S0_MCLK		
112	B8	PTC7	CMP0_IN1	CMP0_IN1	PTC7	SPI0_SIN	USB_SOF_ OUT	I2S0_RX_FS	FB_AD8/ NFC_DATA5			
113	A8	PTC8	ADC1_SE4b/ CMP0_IN2	ADC1_SE4b/ CMP0_IN2	PTC8		FTM3_CH4	I2S0_MCLK	FB_AD7/ NFC_DATA4			
114	D7	PTC9	ADC1_SE5b/ CMP0_IN3	ADC1_SE5b/ CMP0_IN3	PTC9		FTM3_CH5	I2S0_RX_ BCLK	FB_AD6/ NFC_DATA3	FTM2_FLT0		
115	C7	PTC10	ADC1_SE6b	ADC1_SE6b	PTC10	I2C1_SCL	FTM3_CH6	I2S0_RX_FS	FB_AD5/ NFC_DATA2	I2S1_MCLK		
116	B7	PTC11/ LLWU_P11	ADC1_SE7b	ADC1_SE7b	PTC11/ LLWU_P11	I2C1_SDA	FTM3_CH7	I2S0_RXD1	FB_RW_b/ NFC_WE			
117	A7	PTC12	DISABLED		PTC12		UART4_ RTS_b		FB_AD27	FTM3_FLT0		
118	D6	PTC13	DISABLED		PTC13		UART4_ CTS_b		FB_AD26			
119	C6	PTC14	DISABLED		PTC14		UART4_RX		FB_AD25			
120	B6	PTC15	DISABLED		PTC15		UART4_TX		FB_AD24			
121	—	VSS	VSS	VSS								
122	—	VDD	VDD	VDD								
123	A6	PTC16	DISABLED		PTC16	CAN1_RX	UART3_RX	ENET0_ 1588_TMR0	FB_CS5_b/ FB_TSI21/ FB_BE23_ 16_b	NFC_RB		
124	D5	PTC17	DISABLED		PTC17	CAN1_TX	UART3_TX	ENET0_ 1588_TMR1	FB_CS4_b/ FB_TSI20/ FB_BE31_ 24_b	NFC_CE0_b		
125	C5	PTC18	DISABLED		PTC18		UART3_ RTS_b	ENET0_ 1588_TMR2	FB_TBST_b/ FB_CS2_b/ FB_BE15_8_ b	NFC_CE1_b		
126	B5	PTC19	DISABLED		PTC19		UART3_ CTS_b	ENET0_ 1588_TMR3	FB_CS3_b/ FB_BE7_0_b	FB_TA_b		
127	A5	PTD0/ LLWU_P12	DISABLED		PTD0/ LLWU_P12	SPI0_PCS0	UART2_ RTS_b	FTM3_CH0	FB_ALE/ FB_CS1_b/ FB_TS_b	I2S1_RXD1		
128	D4	PTD1	ADC0_SE5b	ADC0_SE5b	PTD1	SPI0_SCK	UART2_ CTS_b	FTM3_CH1	FB_CS0_b	I2S1_RXD0		

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